

Thermal Analysis Input Data Sheet

omo	er Name: Aries P/N:
NOTE: Each simulation set can take anywhere from a day to a week to be completed depending on a variety of factors. It should also be noted that depending on the results of the simulations, changes may need to be made to the design, which may require the socket to be re-quoted. Please provide as much accurate information as possible to support the analysis.	
1)	Thermal Load or Power from the Chip? Watts
	Is the surrounding medium air? Yes No If no, what Gas?
3)	Will this use Pedestal Heat Sink Top Mounted Heat Sink, or is Either Acceptable? Yes No
4)	Can the design incorporate a fan on the heat sink? Yes No
,	Is there any airflow provided by the customer's system acting on the socket? Yes No If yes, please define Air Speed Orientation
6)	Material specifications of the chip? Heat Transfer Coefficient Density Specific Heat (Simulation can be completed with estimated material yielding slight inaccuracy)
7)	Is there a solid model of the device that can be sent? Yes No (Simulation can be completed without model yielding slight inaccuracy)
8)	Maximum Temperature for the device?°C
9)	Maximum temperature of the surrounding medium in the test environment?°C (Environment maximum temperature must be a value lower than the maximum device temperature)
10)	PCB board thickness? inches [] [mm]
11)	Other information regarding size limitations, environment, and other notes for this design?

CUSTOMIZATION: ARIES SPECIALIZES IN CUSTOM DESIGN AND PRODUCTION. SPECIAL MATERIALS, PLATINGS, SIZES, AND CONFIGURATIONS CAN BE FURNISHED, DEPENDING ON QUANTITY.

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